In response to this Election of Species Requirement, Applicant hereby elects Species I, a method for forming a pi-type bus electrode. Claims 1-9 and 11-19 should read on this elected species.

The foregoing election is made with traverse under 37 CFR 1.143 for the reason that all of these species indeed have a single technical characteristic. Specifically, the present application is primarily directed to a method for forming a pi-type bus electrode, in which the step "forming a bus electrode with a pi side on portion of said transparent conductive film layer and on portion of said glass substrate, said pi side being located on said pattern of cavity" is recited (see claim 1, step 3). In order to overcome the edge warp phenomenon of the pi-side of a pi-type bus electrode, the portion of the glass substrate being exposed from the cavity pattern, such that the pi-side of the bus electrode can locate the cavity pattern to improve the adhesion capability. To reduce the edge warp phenomenon, claim 10, step 4 recites "etching said transparent conductive film and forming a cavity pattern in said transparent conductive film and forming a transparent conductive electrode, portion of said glass substrate being exposed from said cavity pattern." Claim 10 recites "wherein one pi side of said pi-type bus electrode being in said cavity and on said glass substrate."

With respect to the present application, in which the pi-type bus electrode is a bus electrode with a pi-side portion of the transparent conductive film layer and portion of the glass substrate, the pi-side being located on the pattern of cavity (as recited in claim 1, step 3). The pi-type bus electrode provides good adhesion capability between the portion of stripes of the pi-type bus electrode and the glass substrate, but wore adhesion capability between the pi-side of the pi-type bus electrode and ITO electrode. Thus, in order to overcome the edge warp phenomenon of the pi-side of pi-type bus electrode, the portion of the glass substrate being exposed from the cavity pattern is such that the pi-side of the bus electrode can locate on the cavity pattern to improve the adhesion capability, and to reduce the edge warp phenomenon (as recited in claim 10, steps 1 to 4, and claim 16, steps 1-6). In view of the foregoing remarks, it is respectfully submitted that while species I and II are patentably distinct, both species should be considered together.

It is therefore respectfully submitted that it should be no undue burden on the Examiner to consider all claims in the single application. Accordingly, this Election of Species Requirement should also be overcome and withdrawn.

In view of the foregoing amendments and remarks, favorable reconsideration and an early Notice of Allowance are earnestly solicited.

In the event there are any outstanding matters remaining in this application, the Examiner is invited to contact the undersigned (703) 205-8000 in the Washington, D.C. area.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

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